



- (51) **International Patent Classification:**
H01L 21/768 (2006.01) *H01L 23/532* (2006.01)
- (21) **International Application Number:**
PCT/US2022/053809
- (22) **International Filing Date:**
22 December 2022 (22.12.2022)
- (25) **Filing Language:** English
- (26) **Publication Language:** English
- (30) **Priority Data:**
17/561,113 23 December 2021 (23.12.2021) US
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(81) **Designated States** (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) **Designated States** (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

(54) **Title:** HYBRID COATING FOR INTEGRATED CIRCUIT DEVICE

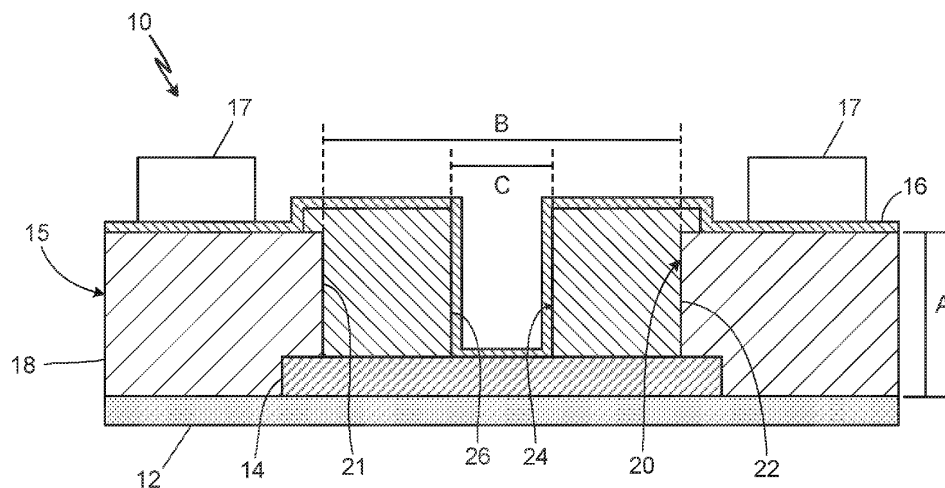


Fig. 1

(57) **Abstract:** An interconnect layer for an integrated circuit device includes a low radio frequency (RF) loss primary coating that forms a main portion of the interconnect layer, an opening formed in the primary coating, a high aspect ratio patternable secondary coating within the opening, and a via formed in the secondary coating. An aspect ratio of the via is greater than an aspect ratio of the opening.

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Published:

— with international search report (Art. 21(3))